

## REMARKS

In the Office Action, Claim 47 is rejected under 35 USC §112, first and second paragraphs. In response, Claim 47 has been amended as previously provided. Support can be found in Applicants' specification, for example, Figures 1-4 and corresponding written description along with Figures 13A-13C and corresponding written description. See, Applicants Published Application No. 2005/0233504, for example, paragraphs 41-49 and 69-71. Therefore, Applicants believe that the §112 rejections with respect to Claim 47 and further its dependent claims should be withdrawn.

Pending Claims 36-50 are rejected as allegedly anticipated or obvious in view of the cited art and combinations thereof. Applicants believe that the anticipation and obviousness rejections should be withdrawn as described in greater detail below.

As previously provided, independent Claims 36, 39 and 41 have been amended to recite, in part, embedding the devices (e.g., one-side devices and other-side devices) into an uncured pressure sensitive adhesive layer. With respect to the other-side devices, these devices are stripped from the first substrate so as to be embedded in the uncured pressure sensitive adhesive layer.

Since the devices 3 are stripped from the temporary adhesive layer 2 before hardening (curing) the pressure sensitive layer 5, the force required for separating the temporary holding substrate 1 and the transfer substrate 4 away from each other is reduced, and the possibility that the temporary holding substrate 1 or the transfer substrate 4 may be damaged at the time of stripping the devices 3 from the temporary adhesion layer 2 is lowered. Particularly, in the case of manufacturing a display apparatus having a large screen, it is necessary to enlarge the area of the transfer substrate 4, so that lowering the possibility of damaging the transfer substrate 4 or the temporary holding substrate 1 should realize a reduction in the manufacturing cost. See, Applicants Published Application No. 2005/0233504, paragraph 49.

In contrast, the cited art, even if properly combinable, fails to disclose or to suggest the claimed invention. For example, the Hayashi reference discloses an adhesive layer 7 partially irradiated with laser beams L from the back surface side of the transfer substrate 6, such that the adhesive layer can be softened. Then, the adhesive layer 7 is cured via cooling wherein the devices 3 are fixed to the adhesive layer 7. See Hayashi, column 11, lines 40-50. In this regard,

the devices 3 in Hayashi are just fixed to, not embedded in, the adhesive layer 7. Moreover, in order to fix the devices in Hayashi to the adhesive layer, softening of the adhesive layer via irradiation and then cooling thereof is required before the adhesive layer is cured to fix the devices to the adhesive layer.

Hayashi does not disclose or suggest stripping the other-side devices from the substrate thereby holding the other-side devices in an embedded state in the uncured pressure sensitive adhesive layer. In contrast, the devices embedded in the uncured pressure sensitive adhesive layer are stripped from the substrate before the uncured pressure sensitive layer is hardened as claimed and previously discussed. Therefore, Applicants believe that one skilled in the art would consider Hayashi different from the claimed invention for at least these reasons. Moreover, Applicants believe that the remaining cited art, alone or even if properly combinable, fails to disclose or suggest the presently claimed invention including newly added claim 51. Accordingly, Applicants believe that the anticipation and obviousness rejections should be withdrawn for at least these reasons, and further respectfully submit that the present application is in condition for allowance.

The Commissioner is hereby authorized to charge deposit account 02-1818 for any fees which are due and owing.

Respectfully submitted,

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